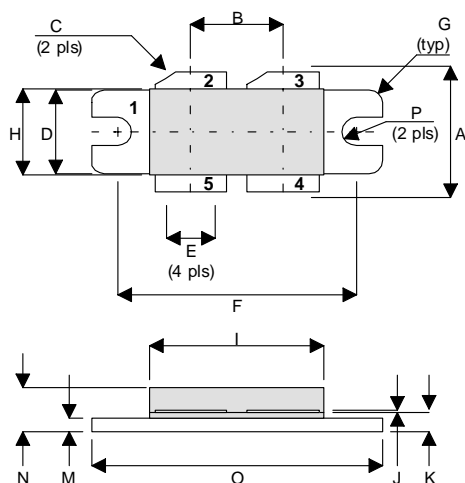


**MECHANICAL DATA**



**D1**

PIN 1	SOURCE (COMMON)	PIN 2	DRAIN 1
PIN 3	DRAIN 2	PIN 4	GATE 2
PIN 5	GATE 1		

DIM	Millimetres	Tol.	Inches	Tol.
A	15.24	0.50	0.600	0.020
B	10.80	0.13	0.425	0.005
C	45°	5°	45°	5°
D	9.78	0.13	0.385	0.005
E	8.38	0.13	0.330	0.005
F	27.94	0.13	1.100	0.005
G	1.52R	0.13	0.060R	0.005
H	10.16	0.15	0.400	0.006
I	21.84	0.23	0.860	0.009
J	0.10	0.02	0.004	0.001
K	1.96	0.13	0.077	0.005
M	1.02	0.13	0.040	0.005
N	4.45	0.38	0.175	0.015
O	34.04	0.13	1.340	0.005
P	1.63R	0.13	0.064R	0.005

**GOLD METALLISED**  
**MULTI-PURPOSE SILICON**  
**DMOS RF FET**  
**125W – 28V – 500MHz**  
**PUSH-PULL**

**FEATURES**

- SUITABLE FOR BROAD BAND APPLICATIONS
- SIMPLE BIAS CIRCUITS
- ULTRA-LOW THERMAL RESISTANCE
- BeO FREE
- LOW Crss
- HIGH GAIN – 13 dB MINIMUM

**APPLICATIONS**

- VHF/UHF COMMUNICATIONS  
from 1 MHz to 500 MHz

$P_D$	Power Dissipation	648W (389W -A Version)
$BV_{DSS}$	Drain – Source Breakdown Voltage *	70V
$BV_{GSS}$	Gate – Source Breakdown Voltage*	±20V
$I_{D(sat)}$	Drain Current*	20A
$T_{stg}$	Storage Temperature	-65 to 150°C
$T_j$	Maximum Operating Junction Temperature	200°C

\* Per Side

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### ELECTRICAL CHARACTERISTICS (T<sub>case</sub> = 25°C unless otherwise stated)

Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<b>PER SIDE</b>					
B <sub>V</sub> DSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0	I <sub>D</sub> = 100mA	70	V
I <sub>D</sub> DSS	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 28V	V <sub>GS</sub> = 0		4 mA
I <sub>G</sub> DSS	Gate Leakage Current	V <sub>GS</sub> = 20V	V <sub>DS</sub> = 0		1 μA
V <sub>GS(th)</sub>	Gate Threshold Voltage*	I <sub>D</sub> = 10mA	V <sub>DS</sub> = V <sub>GS</sub>	1	7 V
g <sub>fs</sub>	Forward Transconductance*	V <sub>DS</sub> = 10V	I <sub>D</sub> = 4A	3.2	mhos
V <sub>GS(th)match</sub>	Gate Threshold Voltage Matching Between Sides	I <sub>D</sub> = 1A	V <sub>DS</sub> = V <sub>GS</sub>		0.1 V
<b>TOTAL DEVICE</b>					
G <sub>PS</sub>	Common Source Power Gain	P <sub>O</sub> = 125W		13	dB
η	Drain Efficiency	V <sub>DS</sub> = 28V	I <sub>DQ</sub> = 2A	50	%
VSWR	Load Mismatch Tolerance	f = 400MHz		20:1	—
<b>PER SIDE</b>					
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 28V	V <sub>GS</sub> = -5V f = 1MHz		240 pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 28V	V <sub>GS</sub> = 0 f = 1MHz		100 pF
C <sub>rss</sub>	Reverse Transfer Capacitance	V <sub>DS</sub> = 28V	V <sub>GS</sub> = 0 f = 1MHz		10 pF

\* Pulse Test: Pulse Duration = 300 μs , Duty Cycle ≤ 2%

### THERMAL DATA

R <sub>THj-case</sub>	Thermal Resistance Junction – Case	Max. 0.27°C / W 0.45 °C / W -A Version
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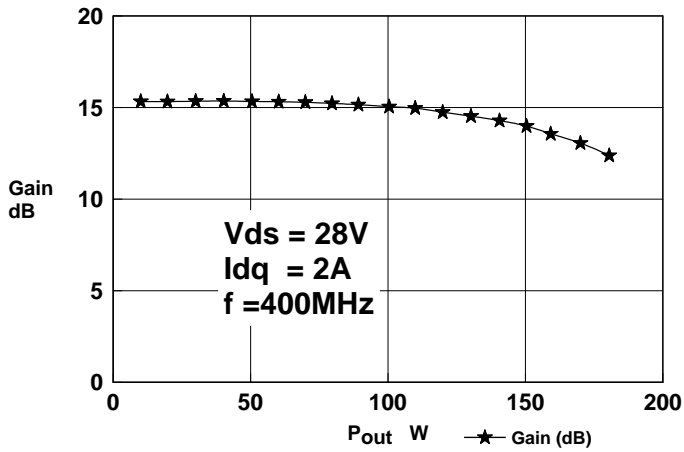


Figure 1 – Gain vs. Power Output.

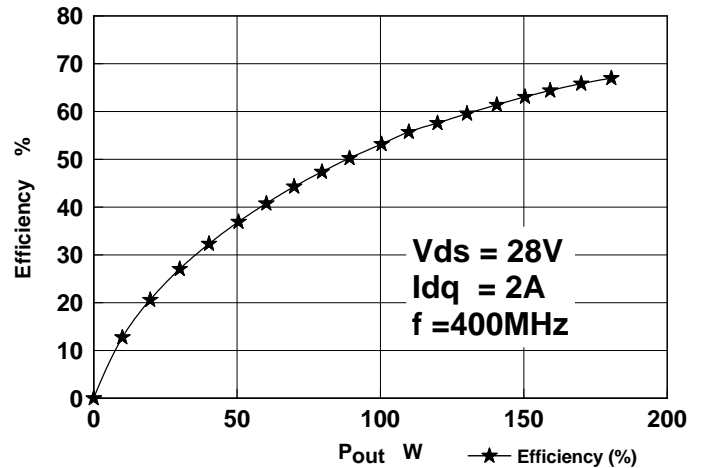


Figure 2 – Efficiency vs. Power Output.

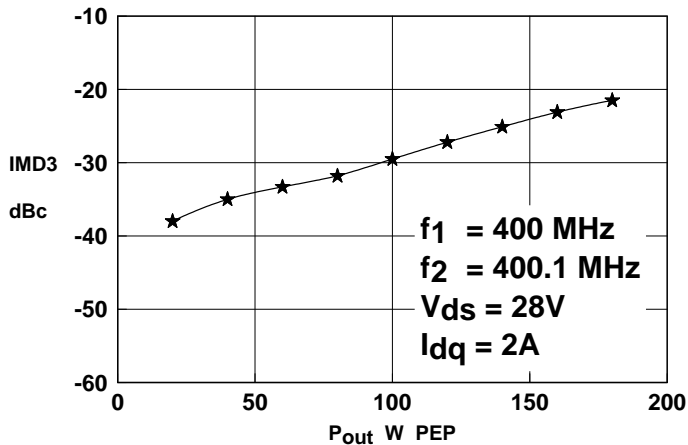
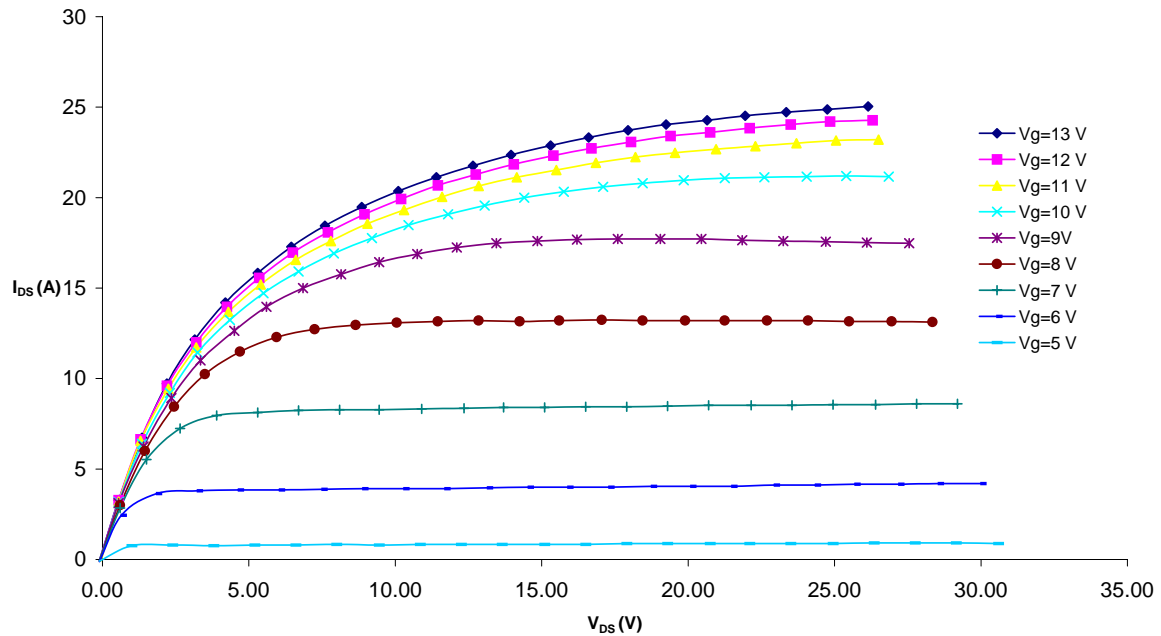
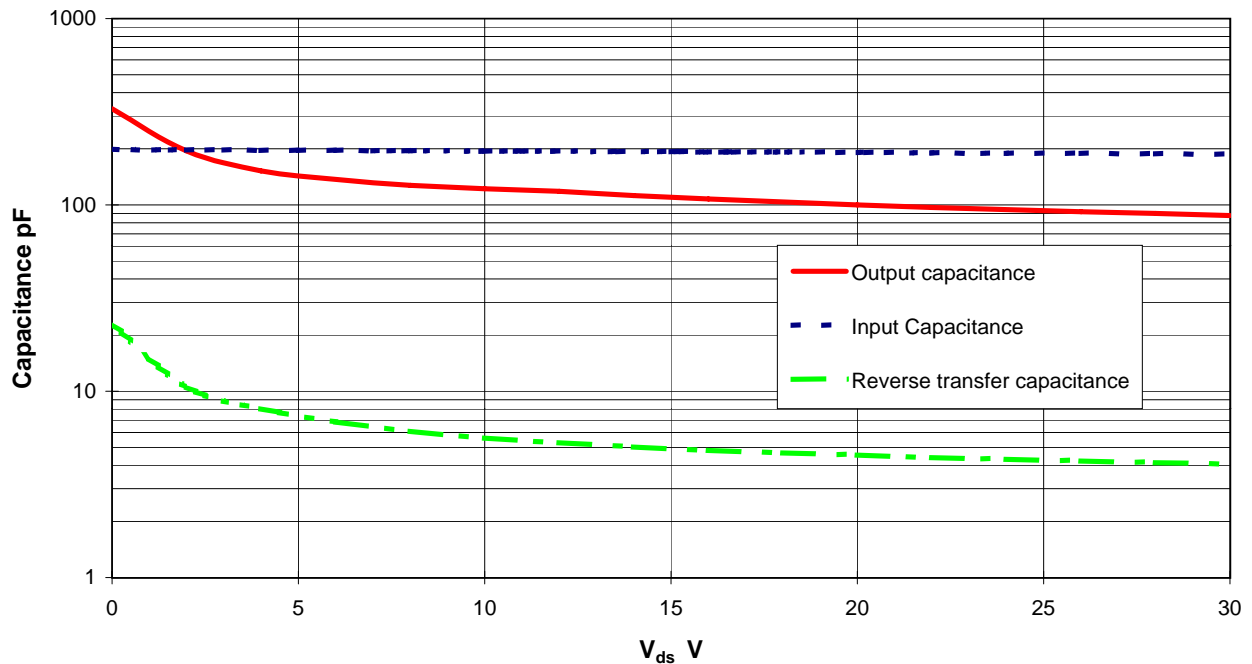


Figure 3 – IMD vs. Power Output

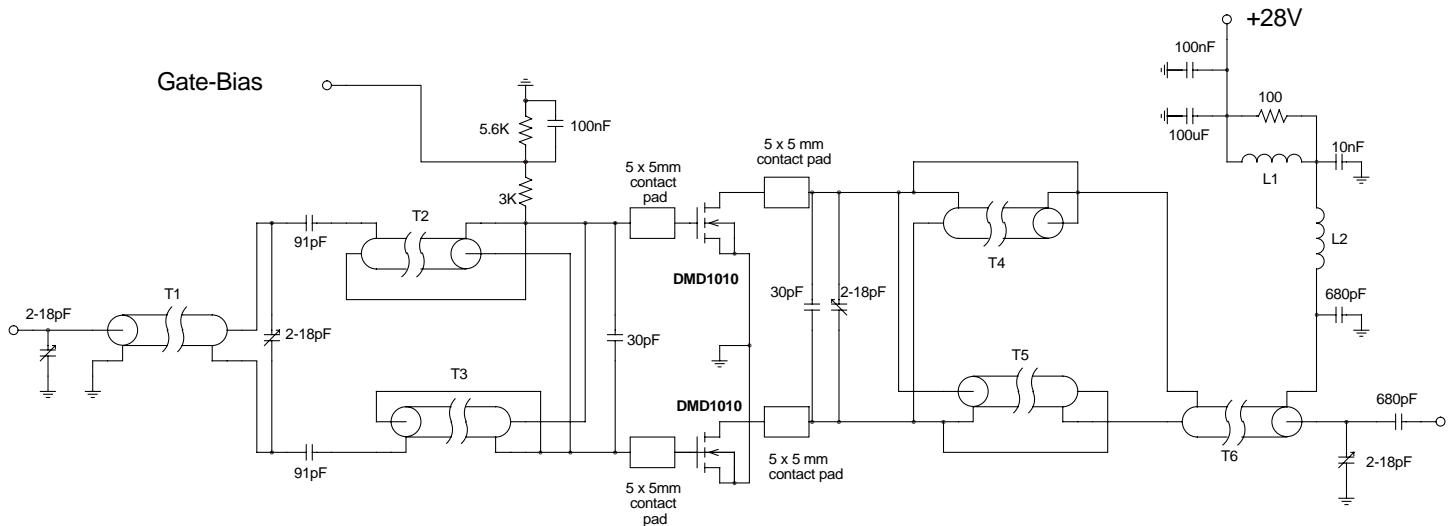


**Figure 4 – Typical IV Characteristics.**



**Figure 5 – Typical CV Characteristics.**

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## DMD1010 TEST FIXTURE

Substrate 1.6mm PTFE/ glass,  $\epsilon_r = 2.5$   
 All microstrip lines  $W = 4.4\text{mm}$

T1	12cm	50 $\Omega$ UT85 semi-rigid coax on ferrite core
T2,3	7.5cm	15 $\Omega$ UT85-15 semi-rigid coax
T4,5	7cm	15 $\Omega$ UT85-15 semi-rigid coax
T6	11cm	50 $\Omega$ UT85 semi-rigid coax on ferrite core
L1	6.5 turns	25swg enamelled copper wire on Fair-Rite FT50B-43 core
L2	6.5 turns	25swg enamelled copper wire, 4mm internal diameter

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